SDLS058

SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158, SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS MARCH 1974 - REVISED MARCH 1988

- Buffered Inputs and Outputs
- Three Speed/Power Ranges Available

TYPES	TYPICAL AVERAGE PROPAGATION TIME	TYPICAL POWER DISSIPATION
ʻ157	9 ns	150 mW
'LS157	9 ns	49 mW
' \$157	5 ns	250 mW
'LS158	7 ns	24 mW
′S158	4 ns	195 mW

applications

- Expand Any Data Input Point
- Multiplex Dual Data Buses
- Generate Four Functions of Two Variables (One Variable Is Common)
- Source Programmable Counters

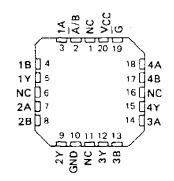
description

These monolithic data selectors/multiplexers contain inverters and drivers to supply full on-chip data selection to the four output gates. A separate strobe input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The '157, 'LS157, and 'S157 present true data whereas the 'LS158 and 'S158 present inverted data to minimize propagation delay time. SN54157, SN54LS157, SN54S157, SN54LS158, SN54S158... J OR Ŵ PACKAGE SN74157... N PACKAGE SN74LS157, SN74S157, SN74LS158. SN74S158... D OR N PACKAGE (TOP VIEW)

А/в[[]	
1A[]2	15 🗍 🖥
1B 🗌 3	14 🗌 4A
1Y∐4	13 🗍 4B
2A 🗍 5	12 🗍 4Y
2B 🗌 6	11 🗍 3A
2Y []7	10 🛛 3B
. GND [8	<u> </u>

SN54LS157, SN54S157, SN54LS158, SN54S158..., FK PACKAGE





NC - No internal connection

	INPL	JTS		OUTP	UT Y
	SELECT Ā/B	A		' 157, 'LS157, 'S157	'LS158 'S158
н	X	x	X	L	H
L	L	L	x	L	н
L	L	н	x	н	L
L	н	х	L	L	н
<u>ι</u>	н	х	н	н	Ł

FUNCTION TABLE

H = high level, L = low level, X = irrelevant

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (See Note 1)	7 V
Input voltage: '157, '\$158	
'LS157, 'LS158	
Operating free-air temperature range: SN54'	– 55°C to 125°C
SN74'	
Storage temperature range	-65°C to 150°C

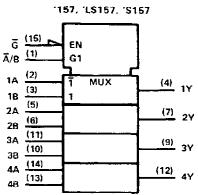
NOTE 1: Voltage values are with respect to network ground terminal.

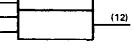
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications our the terms of Team Instruments standard weitherty Production processing does not net scalarily include testing of all parameters.

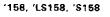


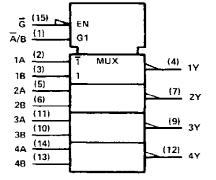
SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158, SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158 **QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS**

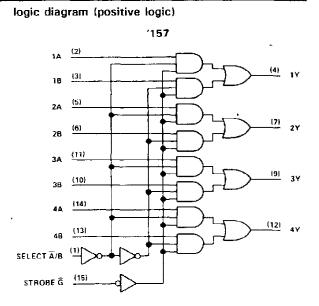
logic symbols[†]









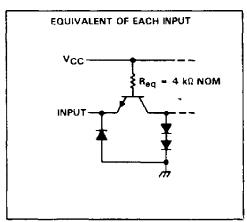


¹These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

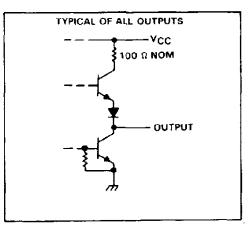
Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs

'157

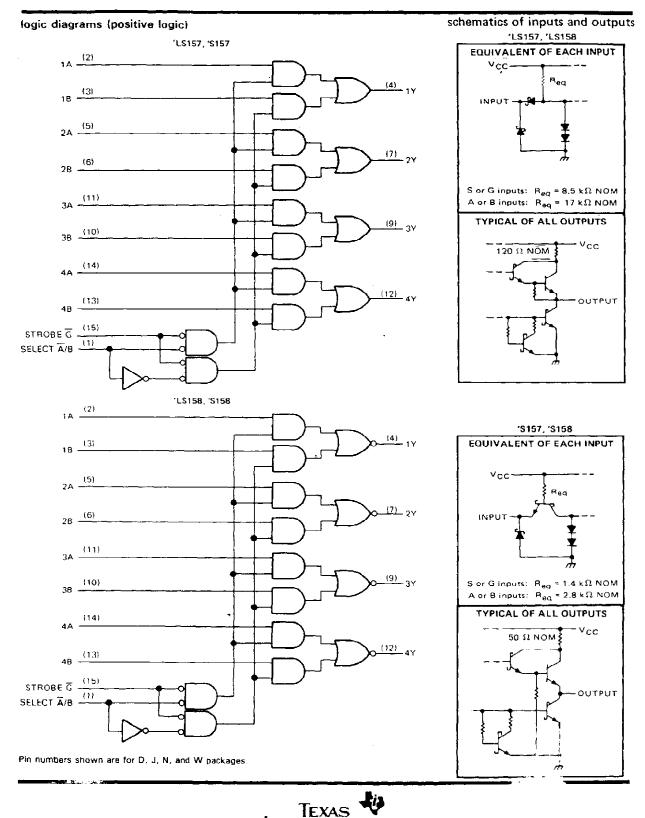


'157





SN54LS157, SN54LS158, SN54S157, SN54S158, SN74LS157, SN74LS158, SN74S157, SN74S158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS



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SN54157, SN74157 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

		SN54157					UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}	4.5	5	5.5	4,75	5	5.25	v
High-level output current, IOH			-800			-800	μA
Low-level output current, IOL			16			16	mA
Operating free-air temperature, TA	-55		125	0		• 70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		7507.0			SN54157 MIN TYP1 MAX		1			
	PARAMÉTÉR	TESTU	TEST CONDITIONS [†]				MIN	TYP [‡]	MAX	
VIH	High-level input voltage			2			2			V
VIL	Low-level input voltage		···	1		0.8			0.8	V
Vik	Input clamp voltage	V _{CC} = MIN,	4 ₁ = - 12 mA	1		- 1.5		~~~~	- 1.5	V
v _{он}	High-level output voltage	V _{CC} = MIN, VIL = 0.8 V.	V _{IH} = 2 V, I _{OH} = -800 µA	2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{1L} = 0.8 V,	V _{IH} = 2 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	v
4	Input current at maximum input voltage	VCC = MAX,	V _I = 5.5 V	-		t			1	mA
ЧΗ	High-level input current	VCC = MAX,	$\overline{V_1} = \overline{2.4 \text{ V}}$			40			40	μA
μL	Low level input current	V _{CC} = MAX,	VI = 0.4 V ·			-1.6	t		-1.6	mА
los	Short-circuit output current §	V _{CC} = MAX		-20		-55	- 18		- 55	mA
1CC	Supply current	VCC = MAX	See Note 2	+	30	48		30	48	mA

¹For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

 $rac{8}{3}$ Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with 4.5 V applied to all inputs and all outputs open.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM (INPUT)	TEST CONDITIONS	MIN	TYP	MAX	ŪNIT
TPLH	<u> </u>			9	14	
tPHL	Data			9	14	ns
1PLH	Strobe G	- CL = 15 pF,		13	20	
трні	30056.0	Rt = 400 ≌. 		14	21	
tPi H	Select A/B		15	23		
tPHL	Select A/B			18	27	ns

1tpLH = propagation delay time, low-to-high-level output

tPHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN54LS157, SN54LS158, SN74LS157, SN74LS158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

		SN54LS'			;	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	_ v
10н	High-level output current	1		-400			-400	μА
IOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							SN54LS	r		SN74LS	•	
	PARAME	IER	TES	T CONDITION	ST	MIN	TYP [‡]	MAX	MIN	түр‡	MAX	UNIT
ViH	High-level inpu	t voltage				2		_	2			v
VIL	Low-level input	voltage		_		1		0.7	[0.8	v
Vik	Input clamp vo	ltage	V _{CC} - MIN,	l _l = -18 mA				-1.5			-1.5	V
vон	High-level outp	ut voltage	V _{CC} = MIN, V _{IL} = MAX,	V _{IH} = 2 V, ^I OH =400	μA	2.5	3.4		2.7	3.4		v
N.c.	Low-level outp		V _{CC} = MIN,	VIH = 2 V.	IOL = 4 mA	1	0.25	0.4		0.25	0.4	v
VOL	Low-level outp	ut vultage	V _{IL} ≃ MAX		I _{OL} = 8 mA					0.35	0.5	Ý
1	Input current at maximum	Ā/B or G	V _{CC} = MAX,	VI = 7 V				0.2			0.2	mА
1 '1	input voltage	A or B		vi - 7 v				0.1			0.1	met 1
1	High-level	Ā/B or G	V MAY	N 27.V	•			40			40	Αu
лн	input current	A or B	V _{CC} = MAX,	V = 2.7 V				20			20	ЦА
ЧL	Low-level	Ā/B or G	Vcc = MAX,	V 0 4 V				-0.8			-0.8	mΑ
11	input current	A or B		0 -0.40				-0.4			-0.4	
los	Short-circuit ou	itput current§	V _{CC} = MAX			-20		-100	-20		-100	mΑ
					'LS157		9.7	16	1	9.7	16	
			V _{CC} = MAX,	See Note 2	'LS158		4.8	8		4.8	8	
'cc	Supply current		V _{CC} = MAX, All A inputs at All other inputs	-	'L\$158		6.5	11		6.5	11	mΑ

¹ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. [‡]All typical values are at V_{CC} = 5 V, T_A = 25[°]C. [§] Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with 4.5 V applied to all inputs and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25° C

PARAMETER	FROM	TEGT CONDUCIONS	'L\$157			T	UNIT		
FANAIVICIEN 1	(INPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	ΤΥΡ	MAX	U.I.I.
<u>чрен</u>			~	9	14		7	12	
трнц	Data			9	14	[10	15	ns
^{tPLH}		$C_L = 15 pF$		13	20		11	17	
tPHL	Strobe G	$R_{L} = 2 k\Omega_{c}$		14	21		18	24	ns
^t PLH	Select A/B	See Note 3		15	23		13	20	
TPHL	Select A/B			18	27		16	24	1 ns

ItpLH = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output NOTE 3: Load circuits and voltage diagrams are shown in Section 1.

SN54S157, SN54S158, SN74S157, SN74S158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

		SN54S157 SN54S158				SN74S157 SN74S158			
	MIN	NOM	ΜΑΧ	MIN	NOM	MAX			
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V		
High-level output current, IOH			-1			-1	mA		
Low-level output current, IOL			20			20	mΑ		
Operating free-air temperature, TA	55		125	0		70	°C		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TES	TCONDITIONS	SN54S157 JS [†] SN74S157					58 58	UNIT	
			(MIN	τγρ‡	ΜΑΧ	MIN	тур‡	MAX	
⊻ін	High-level input voltage					z	_		2			V
VIL	Low-level input voltage		[0.8	[-		0.8	V
VIK	Input clamp voltage		V _{CC} = MIN,	1 ₁ = -18 mA				-1.2			-1.2	V
			V _{CC} = MIN.	V _{1H} = 2 V.	Series 545	2.5	3.4		2.5	3.4		v
⊻он	High-level output voltage		VIL = 0.8 V,	I _{ОН} = —1 mA	Series 74S	2.7	3.4		2.7	3.4		ľ
Vol	Low-level output voltage		$V_{CC} = MIN,$ $V_{UL} = 0.8 V$	V _{IH} = 2 V, I _{OI} = 20 mA				0.5		_	0.5	v
<u> </u>	Input current at maximur	n input voltage		<u> </u>	,	<u> </u>		1	<u>+</u>		1	mA
ЧΗ	- Migh-level input current h	Ā/B pr G A or B	V _{CC} = MAX,	V ₁ = 2.7 V		ļ		100 50			100	μA
4	Low-level input current	A/B or G A or B	V _{CC} = MAX,	V ₁ = 0.5 V				4			4	mA
1 _{OS}	Short-circuit ouput currer	ntš	V _{CC} = MAX	· · · ·····		-40		-100	_40		-100	mA
1	Supply and		V _{CC} = MAX, See Note 2	All inputs at 4.	5 V,		50	78		39	61	
ICC	Supply current			A inputs at 4.5 at 0 V, See N							81	mA

÷. •

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 \ddagger All typical values are at V_{CC} = 5 V, T_A = 25°C.

\$Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

Note 2: ICC is measured with all outputs open.

witching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER	FROM	TEST CONDITIONS	1	N54S1 N74S1		SN54S158 SN74S158			
	(INPUT)		MIN	ТҮР	MAX	MIN	түр	MAX	ns ns
трцн	Data			5	7.5		4	6	ns
tPHL		C 15 ρF, R1 = 280 Ω,		4.5	6.5		4	6	
^t PLH	Strobe G			8.5	12.5		6.5	11.5	
tpHL	Strobe G	See Note 3		7.5	12		7	12	
tPLH	Select A/B	See 1401e S		9.5	15		8	12	ns
1PHL	Select A/B			9.5	15		8	12	

 \P_{tPLH} = propagation delay time, low-to-high-level output

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





25-Oct-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
76002012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76002012A SNJ54LS 157FK	Samples
7600201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201EA SNJ54LS157J	Samples
7600201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201FA SNJ54LS157W	Samples
76033012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76033012A SNJ54LS 158FK	Samples
7603301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7603301EA SNJ54LS158J	Samples
JM38510/07903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BEA	Samples
JM38510/07903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BFA	Samples
JM38510/07904BEA	OBSOLETI	E CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/07904BFA	OBSOLETI	E CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/30903B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30903B2A	Samples
JM38510/30903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BEA	Samples
JM38510/30903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BFA	Samples
M38510/07903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BEA	Samples
M38510/07903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07903BFA	Samples
M38510/30903B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30903B2A	Samples
M38510/30903BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BEA	Samples
M38510/30903BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30903BFA	Samples



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	San
SN54157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54157J	San
SN54LS157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS157J	San
SN54LS158J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS158J	Sar
SN54S157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S157J	Sar
SN54S158J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN74157N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	Sa
SN74LS157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	Sa
SN74LS157DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	Sa
SN74LS157DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	Sa
SN74LS157DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	Sa
SN74LS157DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS157	Sa
SN74LS157N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS157N	Sa
SN74LS157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS157NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS157N	Sa
SN74LS157NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS157	Sa
SN74LS158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS158	Sa
SN74LS158DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS158	Sa
SN74LS158DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS158	Sa



PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN74LS158N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS158N	Sampl
SN74LS158N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS158NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS158N	Sampl
SN74LS158NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS158	Sampl
SN74S157N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70	SN74S157N	
SN74S157N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74S158D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S158DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S158N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74S158N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SNJ54157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54157J	Sampl
SNJ54157W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54157W	Samp
SNJ54LS157FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76002012A SNJ54LS 157FK	Samp
SNJ54LS157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201EA SNJ54LS157J	Samp
SNJ54LS157W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600201FA SNJ54LS157W	Samp
SNJ54LS158FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76033012A SNJ54LS 158FK	Samp
SNJ54LS158J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7603301EA SNJ54LS158J	Samp
SNJ54S157FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 157FK	Samp
SNJ54S157J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S157J	Samp
SNJ54S157W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S157W	Samp
SNJ54S158FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		



25-Oct-2016

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54S158J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S158W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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25-Oct-2016

OTHER QUALIFIED VERSIONS OF SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158, SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158 :

• Catalog: SN74157, SN74LS157, SN74LS158, SN74S157, SN74S158

• Military: SN54157, SN54LS157, SN54LS158, SN54S157, SN54S158

NOTE: Qualified Version Definitions:

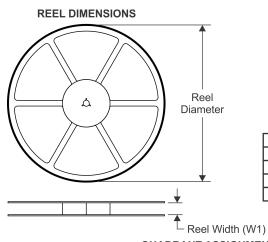
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

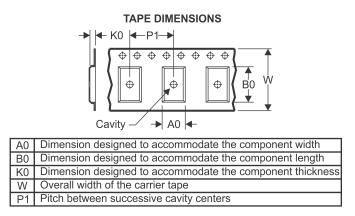
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



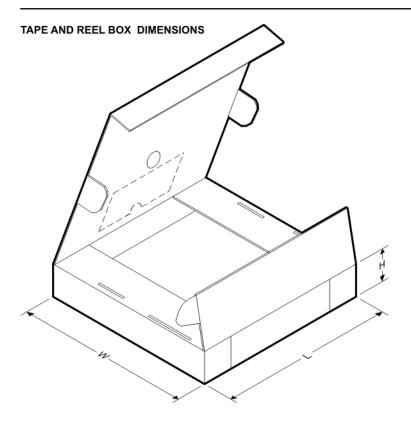
*	All dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LS157DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
	SN74LS158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
ſ	SN74LS158NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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PACKAGE MATERIALS INFORMATION

8-Apr-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS157DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS158DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS158NSR	SO	NS	16	2000	367.0	367.0	38.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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